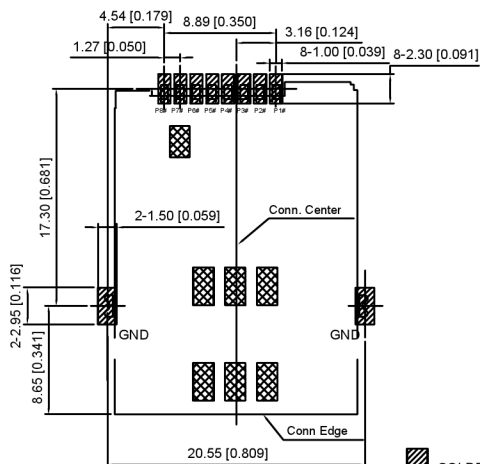
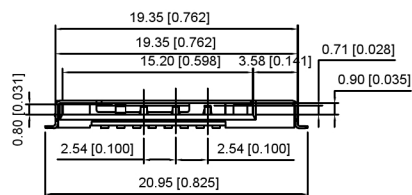


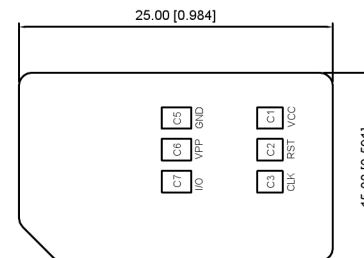
**NOTES:**

- 1) MATERIAL:  
HOUSING: LCP UL 94V-0  
TERMINAL: COPPER ALLOY , T=0.15  
SHELL: SUS, T=0.15  
MYLAR: POLYESTER
- 2) FINISH :  
TERMINAL: GOLD FLASH PLATED ON CONTACT AREA;  
GOLD FLASH PLATING ON SOLDER TAILS, WITH ENTIRE CONTACT UNDERPLATED 50u"Min, NICKEL  
SHELL: 50u"Min. NICKEL UNDERPLATED OVERALL , GOLD FLASH PLATED ON SOLDER TAILS
- 3) INFRARED REFLOW SOLDERING: 10sec. Min. at 260 <sup>+10</sup><sub>-0</sub>



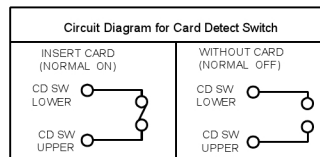
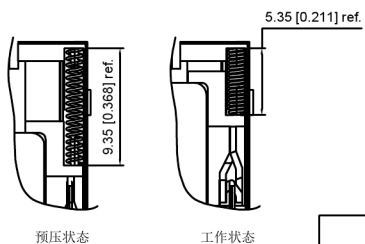
▨ SOLDER AREA  
▩ NONE CIRCUIT DIAGRAM AREA

RECOMMENDED PCB LAYOUT(TOP VIEW)  
GENERAL TOLERANCES:±0.05



**2FF SIM CARD**

PIN NO.	DESCRIPTION
P1#	C1:VCC
P2#	C5:GND
P3#	C2:RST
P4#	C6:VPP
P5#	C3:CLK
P6#	C7:POL
P7#	POL
P8#	DET



ITEM	PAPT NAMF	QTY	MATERIAL	FINISHING
③	Shell	1	SUS	
②	Terminal	8	COPPER ALLOY	
①	Housing	1	LCP UL 94V-0	BLACK

广东星坤科技股份有限公司

Δx		日期
Δx		日期
Δx		日期
MARK		日期

文件工程章

DESCRIPTION	DATE	REVISED	APPROVED	UNSPECIFIED TOLERANCES

DSND	SCALE: N/A	MODEL TYPE: SIM CARD CONN
DWN	VIEW:	PART NO.:
CHKD	UNIT: mm/in	DWG NO.:
APPD	SIZE: A4	<b>XKSIM-115</b>



XKB INDUSTRIAL PRECISION CO., LIMITED

WEIGHT	SHEET	REVISION
	1/1	A0